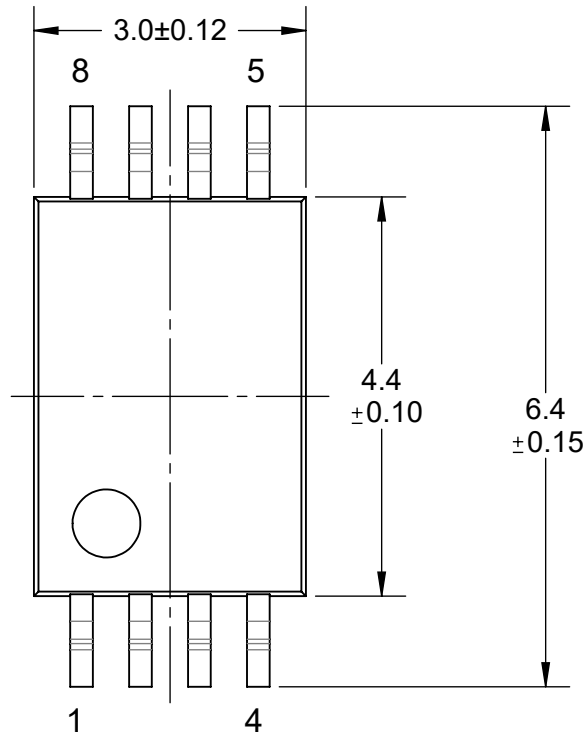
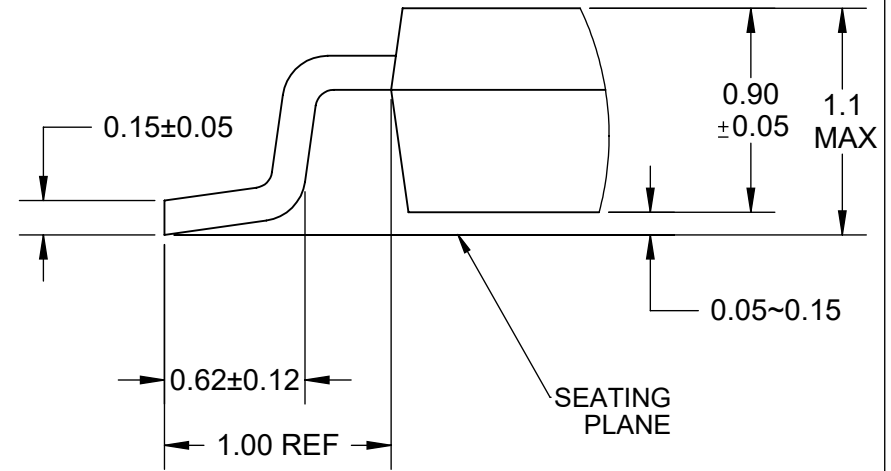


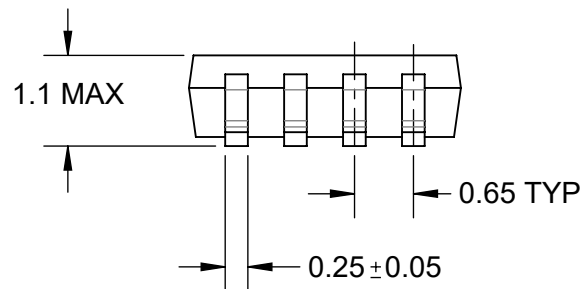
TOP VIEW



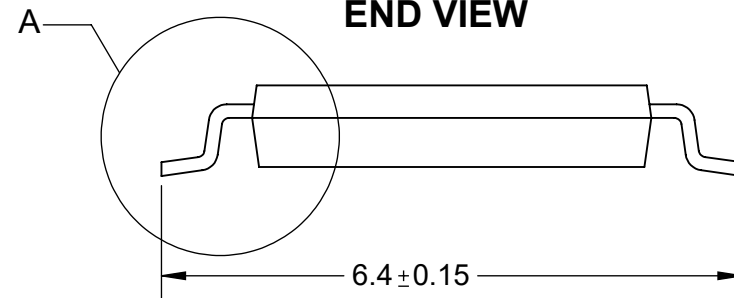
DETAIL A



SIDE VIEW



END VIEW

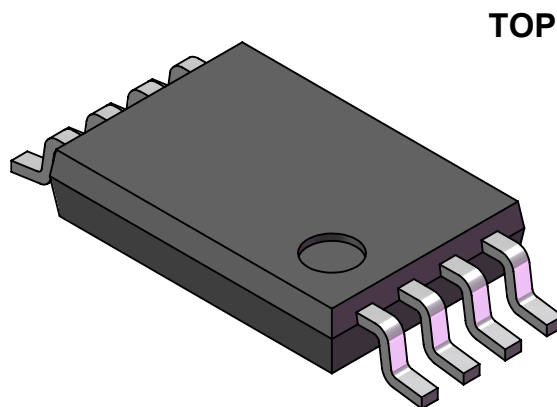
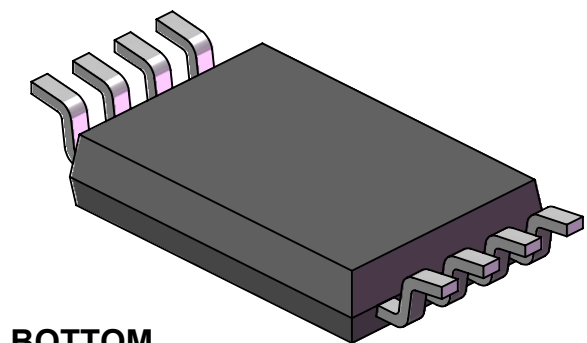
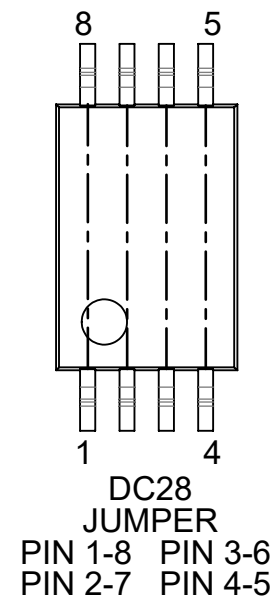
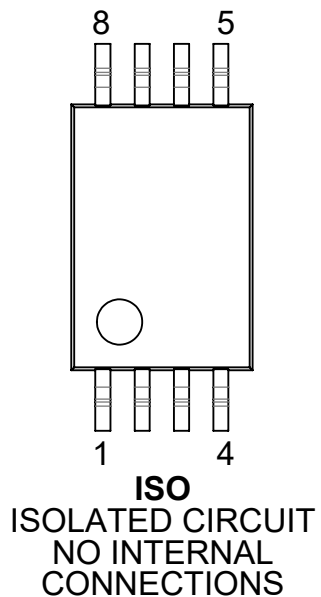
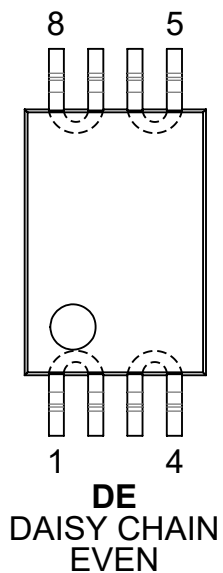


Notes: (Unless Otherwise Specified)

1. DIMENSIONS mm.
2. SEE DAISY CHAIN JUMPER DIAGRAMS (PAGE 2).
3. SEE PART NUMBER CONFIGURATION (PAGE 3).
4. RECOMMENDED PC BOARD LAYOUT PATTERN (PAGE 5).

APPROVALS	DATE	TopLine®			
DRAWN T.Au	9/9/2020				
ENG M. Hart	9/9/2020	TITLE TSSOP8 OUTLINE PACKAGE			
MFG		SCALE	SIZE	DRAWING NO.	REV
QA		10:1	A	120806	A
CUST		DO NOT SCALE DRAWING			SHEET 1 OF 6
REVISED					

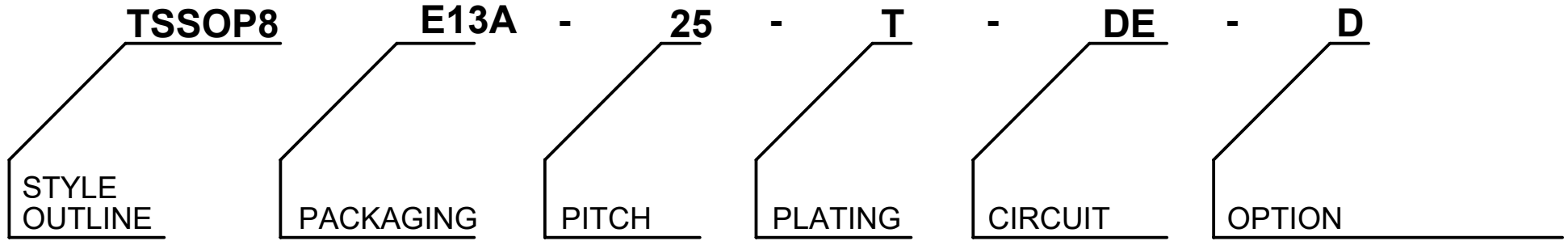
INTERNAL WIRING CIRCUIT (JUMPER) PART NUMBER SUFFIX TOP VIEW



MODEL

TopLine®			
TITLE TSSOP8 OUTLINE PACKAGE			
SCALE	SIZE	DRAWING NO.	REV
10:1	A	120806	A
DO NOT SCALE DRAWING			SHEET 2 OF 6

PART NUMBERING SYSTEM



THIN SHRINK SMALL
OUTLINE
PACKAGE
8 LEADS

M = TUBE
E7A = 7" REEL
E13A = 13" REEL
E = CUT TAPE

25 = 0.65mm
OPTIONAL

T =
Pb-FREE
RoHS
LEAD FREE

Sn100
MATTE TIN

BLANK=
Sn85/Pb15

DE - DAISY
CHAIN EVEN

ISO = ISOLATED
CIRCUIT

DX = CUSTOM
JUMPER

DC28 =
1~8 , 2~7
3~6, 4~5

BLANK - COMMERCIAL GRADE
(STANDARD)

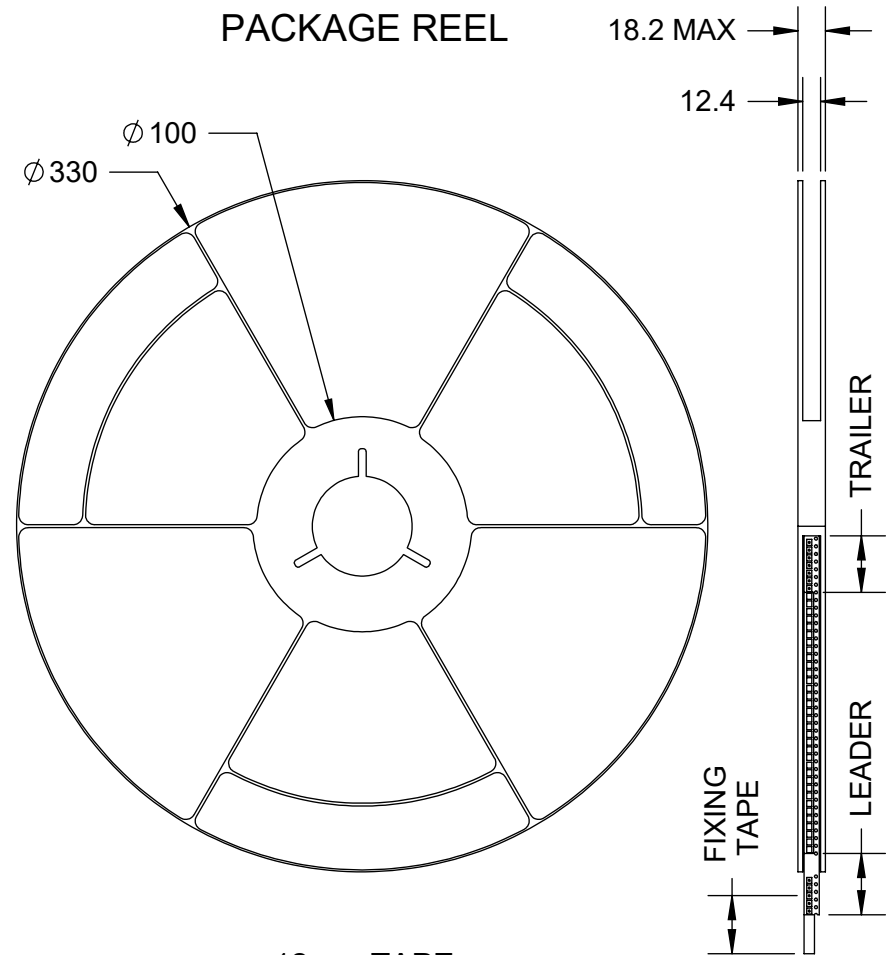
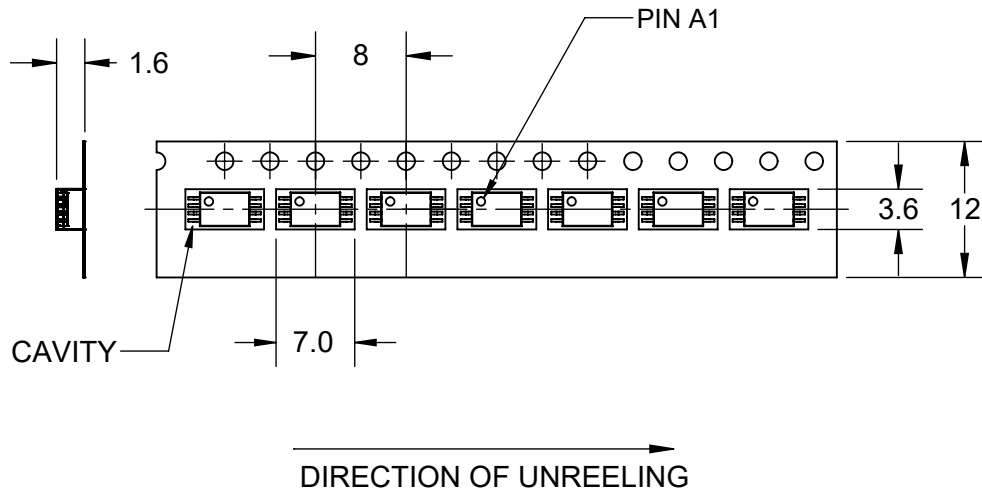
D = INTERNAL DUMMY DIE

PART NUMBER	SHORTED PINS	NOTES	RoHS Pb-FREE	MSL LEVEL
TSSOP8E13A25-T	N/A	DUMMY	YES	1
TSSOP8E13A25-T-ISO	NONE	ISOLATED	YES	1
TSSOP8E13A25-T-DE-D	1~2 , 3~4 5~6, 7~8	DAISY CHAIN	YES	1
TSSOP8E13A-T-DC28D	1~8 , 2~7 3~6, 4~5	JUMPER	YES	1

TopLine®			
TITLE		TSSO8 OUTLINE PACKAGE	
SCALE	SIZE	DRAWING NO.	REV
NONE	A	120806	A
DO NOT SCALE DRAWING			SHEET 3 OF 6

TAPE SPECIFICATION TSSOP8 SURFACE MOUNT DEVICE

TAPE DIMENSIONS

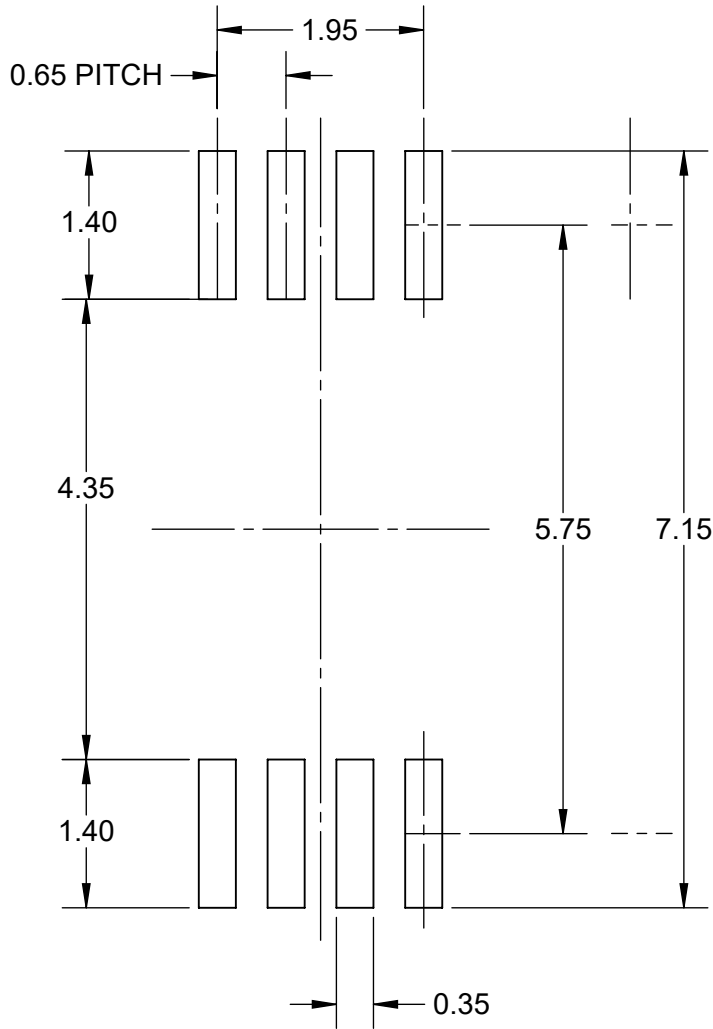


12mm TAPE
1000~3000 PCS

ALL DIMENSIONS IN mm.

TopLine®			
TITLE		TSSOP8 OUTLINE PACKAGE	
SCALE	SIZE	DRAWING NO.	REV
3:2	A	120806	A
DO NOT SCALE DRAWING			SHEET 4 OF 6

PCB BOARD LAND PATTERN

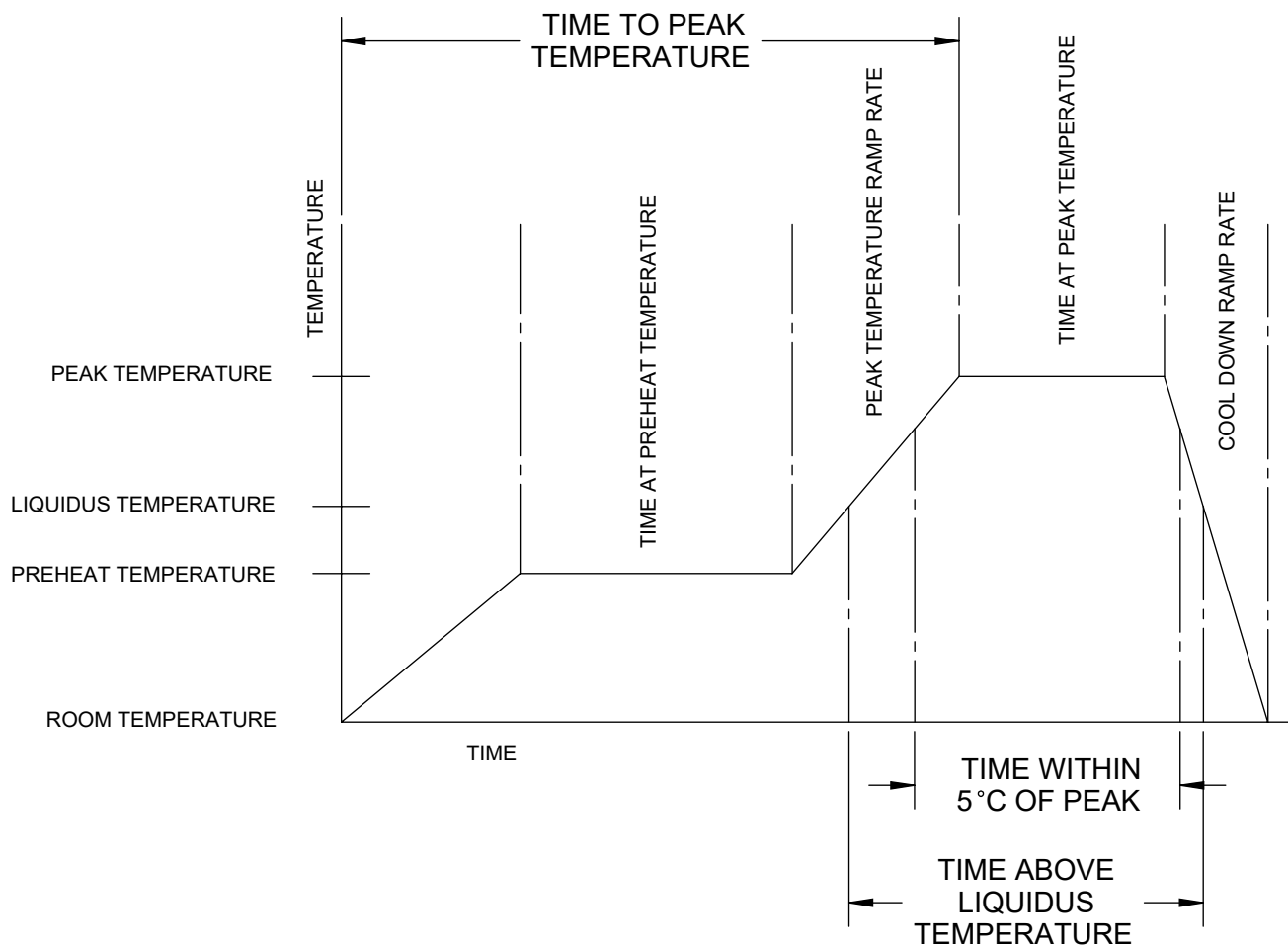


Notes: (Unless Otherwise Specified)

1. DIMENSIONS ARE IN mm.
2. PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE.
3. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.

TopLine®			
TITLE		TSSOP8 OUTLINE PACKAGE	
SCALE	SIZE	DRAWING NO.	REV
12:1	A	120806	A
DO NOT SCALE DRAWING			SHEET 5 OF 6

LEAD FREE REFLOW PROFILE OF SMD PACKAGE



DESCRIPTION	REQUIREMENT
AVERAGE PREHEAT RAMP RATE	3°C /SECOND MAXIMUM
PREHEAT TEMPERATURE	150°C MINIMUM, 200°C MAXIMUM
PREHEAT TIME	60 TO 80 SECONDS
RAMP TO PEAK	3°C /SECOND MAXIMUM
TIME OVER LIQUIDUS (217°C)	60 TO 150 SECONDS
PEAK TEMPERATURE	260°C +0/-5°C
TIME WITHING 5°C OF PEAK	20 TO 40 SECONDS
RAMP - COOL DOWN	6°C /SECONDS MAXIMUM
TIME 25°C TO PEAK	6 MINUTES MAXIMUM

TopLine®			
TITLE		TSSOP8 OUTLINE PACKAGE	
SCALE	SIZE	DRAWING NO.	REV
NONE	A	120806	A
DO NOT SCALE DRAWING			SHEET 6 OF 6